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Abstract

Semiconductor component and production method

Semiconductor component, in particular a light-emitting diode, whose semiconductor body (1) has a mesa structure. The curved side surface (9) is concave adjacent to the front side (2) of the semiconductor body (12) and convex adjacent to the rear side (3). This shaping distinctly increases the external quantum efficiency of the light-emitting diode according to the invention. In an advantageous method for producing a plurality of semiconductor components according to the invention, mesa etching is only carried out after the separation of a semiconductor wafer (10) into individual chips.

(Figure 1)